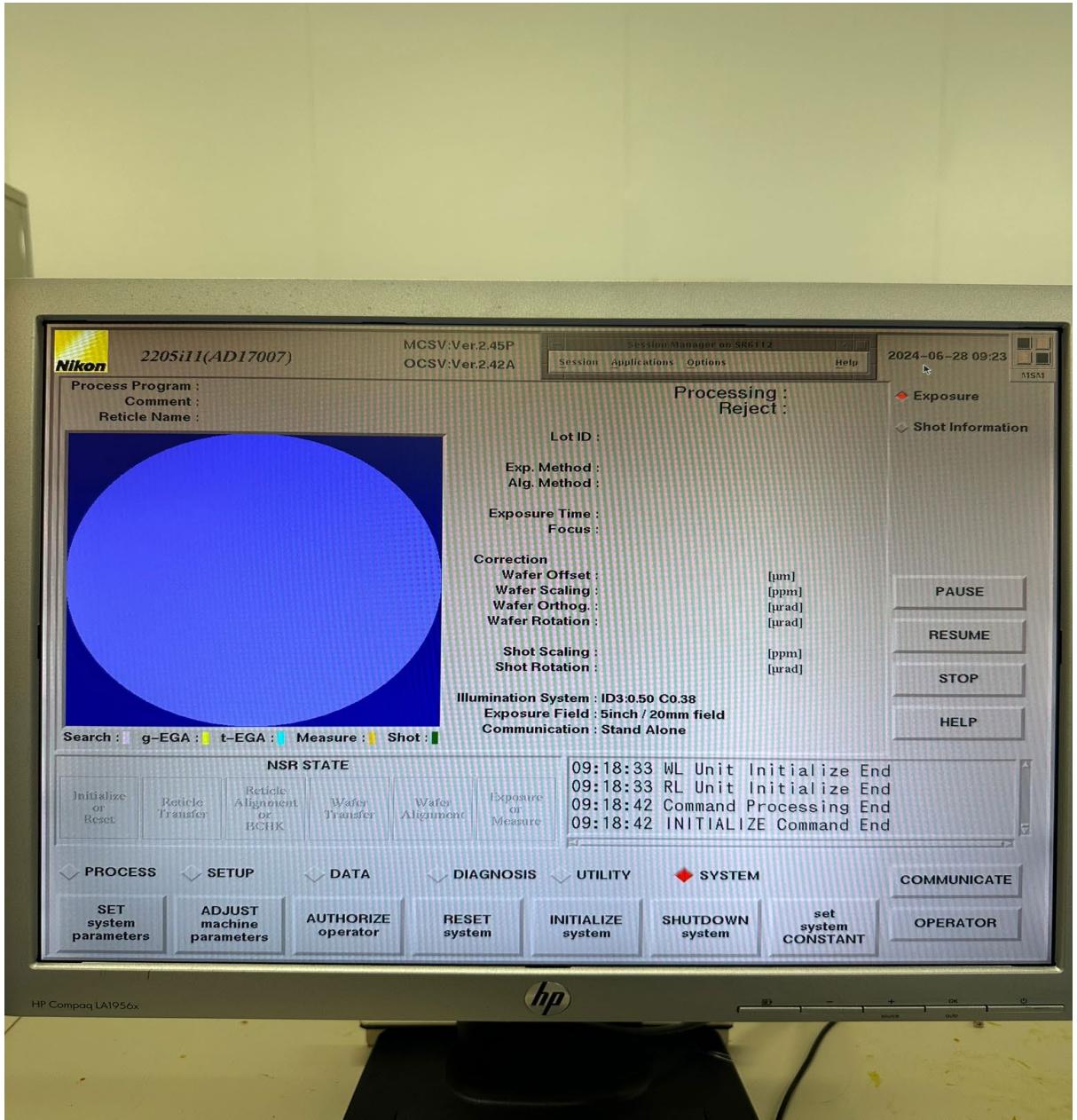
NSR-2205i11D S/N:- 1105183


enthält oder
vom Kyoto-
reibhausgase
(GWP
(Global Warming Potential)
sgase
CHSEN
KÄLTE
NIKON CORPORATION
201-9, OH-AZA, MIIZUGAHARA
KUMAGAYA, SAITAMA, JAPAN
MANUFACTURED SEP 1995
Nikon STEP AND
REPEAT SYSTEM
MODEL NSR-2205i11D No. 1105183
THIS PRODUCT COMPLIES WITH HHS
PERFORMANCE STANDARDS FOR LASER
PRODUCT 21 CFR 1040.10 AND 1040.11.
CE

Nteklitho Total Lithography Solutions

Nteklitho Total Lithography Solutions



Nteklitho
GLOBAL STEPPER & SCANNER PRODUCTS AND SOLUTIONS

Nteklitho Total Lithography Solutions

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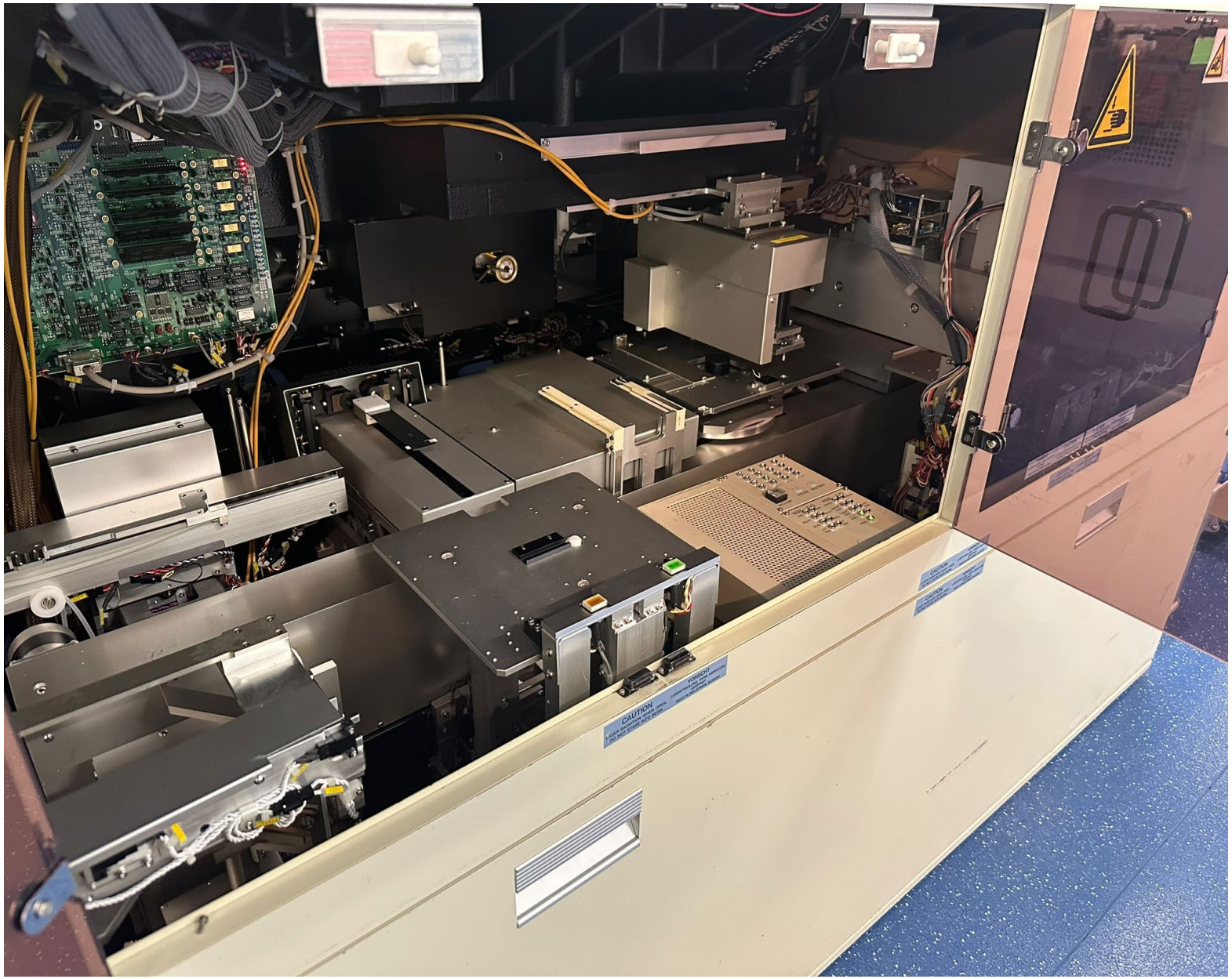
GLOBAL STEPPER & SCANNER PRODUCTS AND SOLUTIONS

Nteklitho Total Lithography Solutions



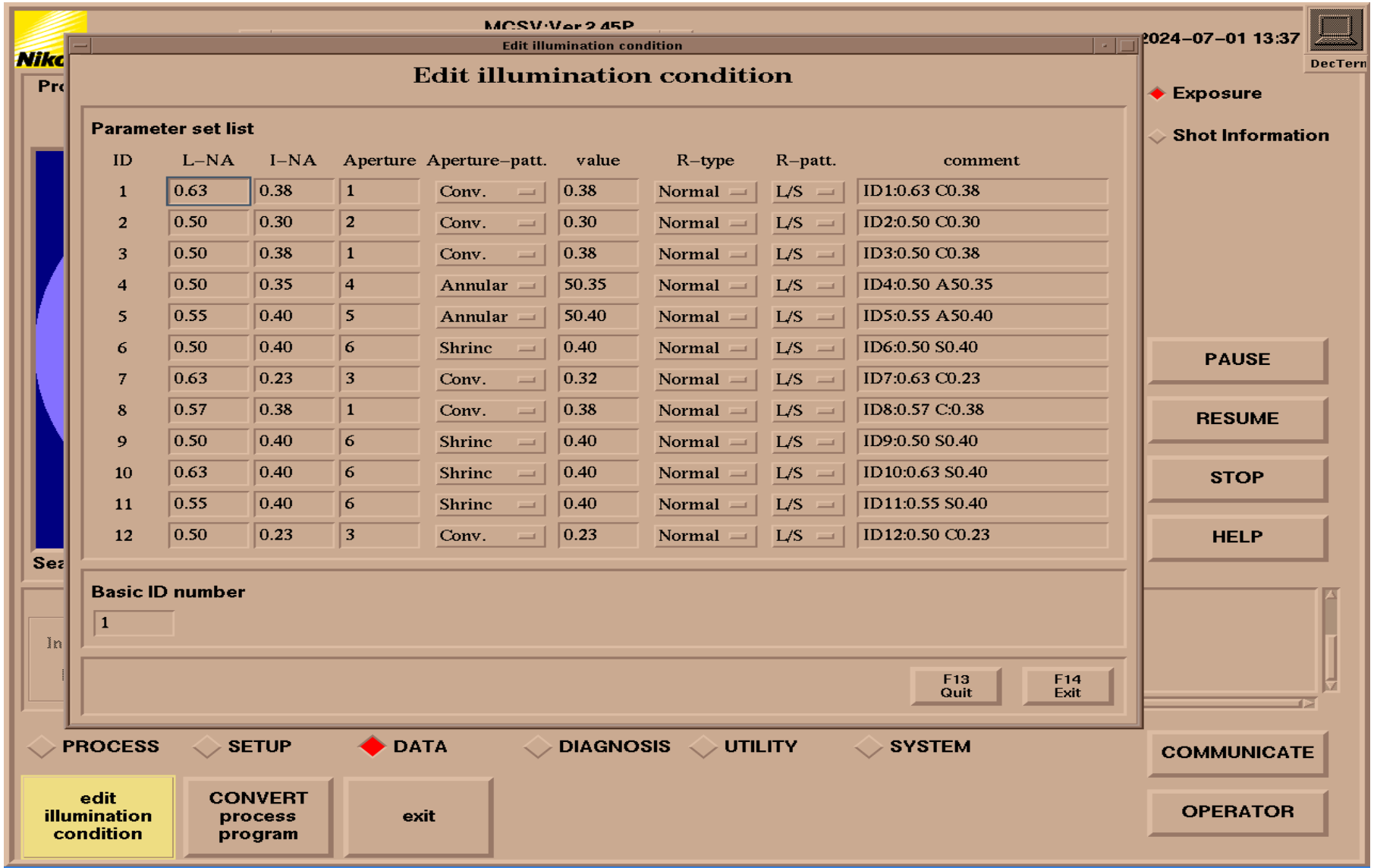
Nteklitho
GLOBAL STEPPER & SCANNER PRODUCTS AND SOLUTIONS

Nteklitho Total Lithography Solutions

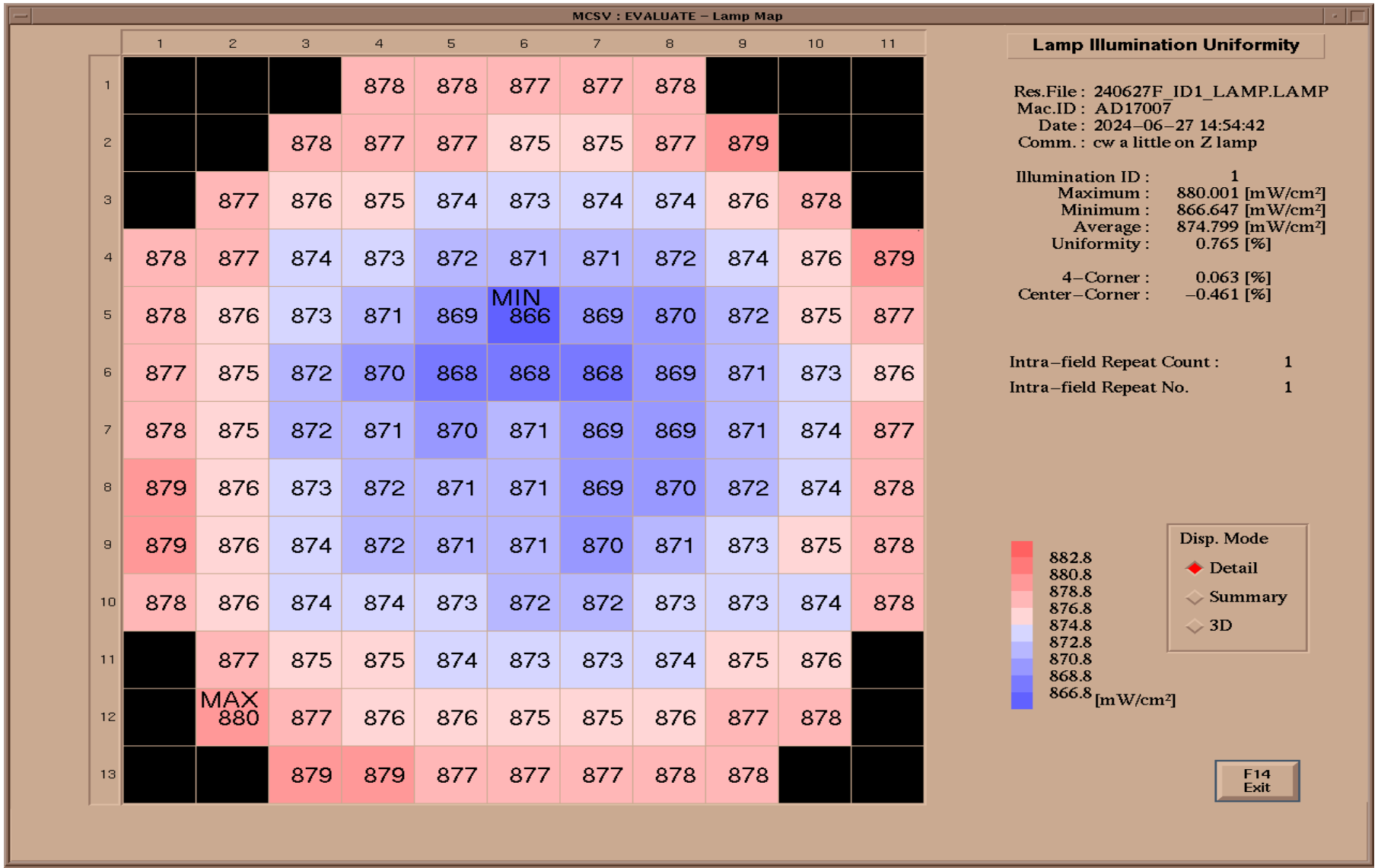
NSR-2205i11D S/N:- 1105183

- Date of Manufacture: 01 Sep 1995
- Serial Number: 1105183
- Resolution: 0.35µm
- Computer Type: Nest-V
- Reticle Size: 5inch
- Field Sizes: 15 / 17.5 / 20mm
- Wafer Size: 8 inch Notch
- Reticle Libraries: 1
- Wafer Loader: Type 2
- In – Line: Left
- Wafer Loader prealignment 2: Yes
- Barcode Reader: Yes
- Wafer Loader Indexers: 2
- FIA: Yes
- LSA: Yes
- LIA: No
- Autofocus: 5 Point
- Levelling: Yes
- Chuck Type: Ceramic ring chuck
- Illuminator: Shrinc 1
- Illuminator Power : 1750 Watts
- MCSV:2.45P
  OCSV: 2.42A
  TOOL: 2.51A
- PPD: No
- FC2 : Yes

Illuminator Table



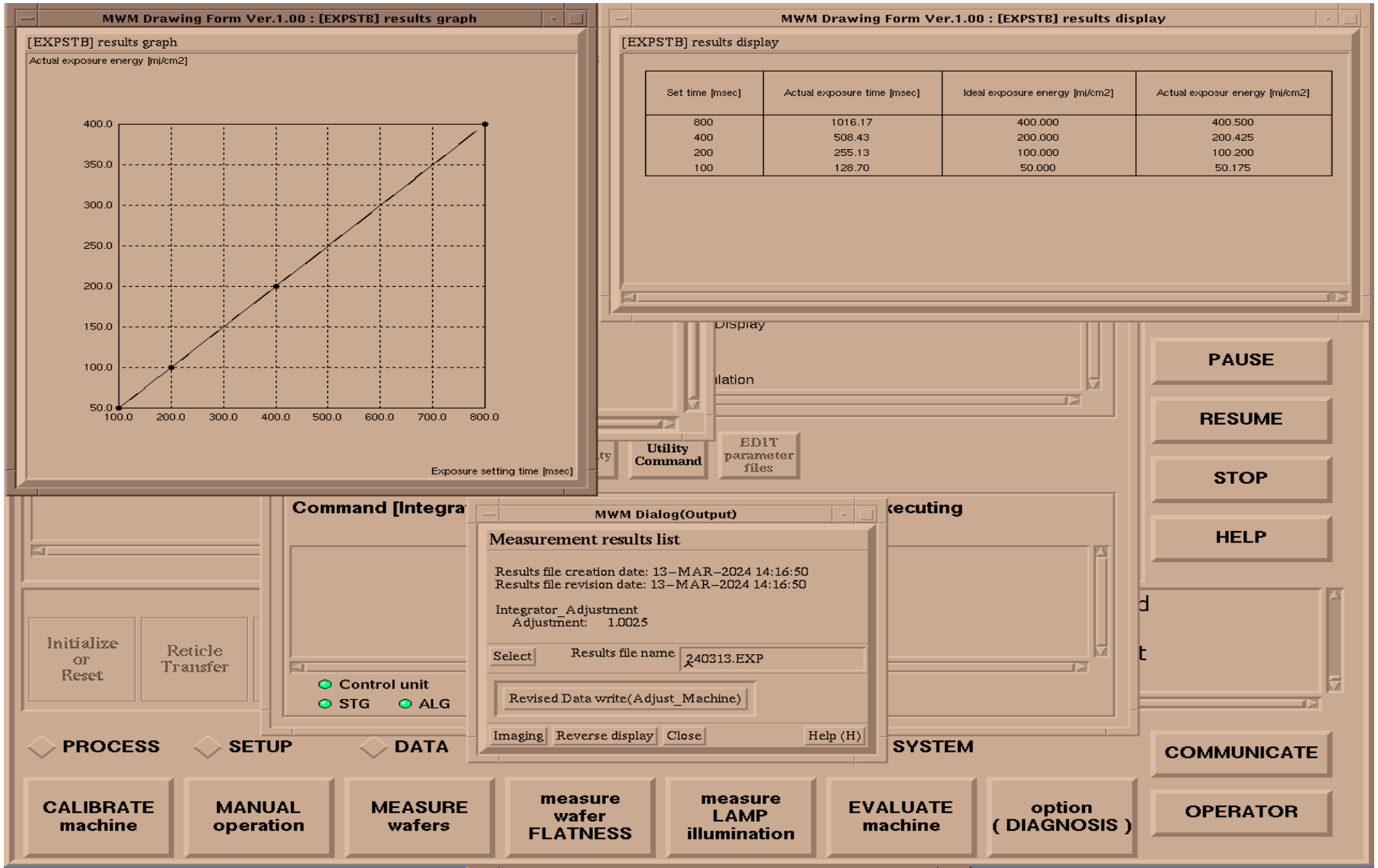
Illuminator Uniformity



	1	2	3	4	5	6	7	8	9	10	11
1				878	878	877	877	878			
2			878	877	877	875	875	877	879		
3		877	876	875	874	873	874	874	876	878	
4	878	877	874	873	872	871	871	872	874	876	879
5	878	876	873	871	869	MIN 866	869	870	872	875	877
6	877	875	872	870	868	868	868	869	871	873	876
7	878	875	872	871	870	871	869	869	871	874	877
8	879	876	873	872	871	871	869	870	872	874	878
9	879	876	874	872	871	871	870	871	873	875	878
10	878	876	874	874	873	872	872	873	873	874	878
11		877	875	875	874	873	873	874	875	876	
12		MAX 880	877	876	876	875	875	876	877	878	
13			879	879	877	877	877	878	878		

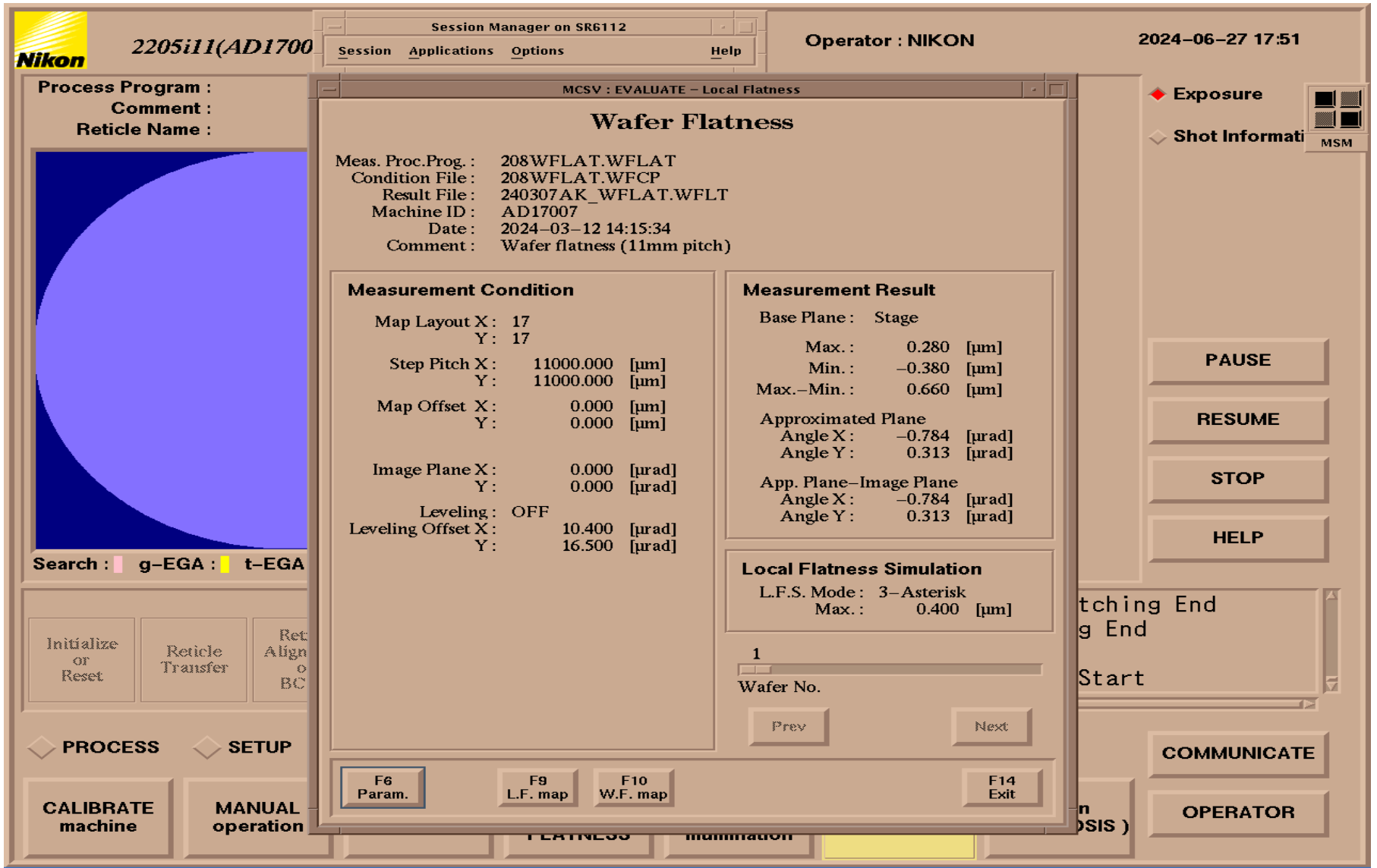
OEM Spec
Power < 800 mW/cm2
Uniformity < 1.5%

Exposure Accuracy



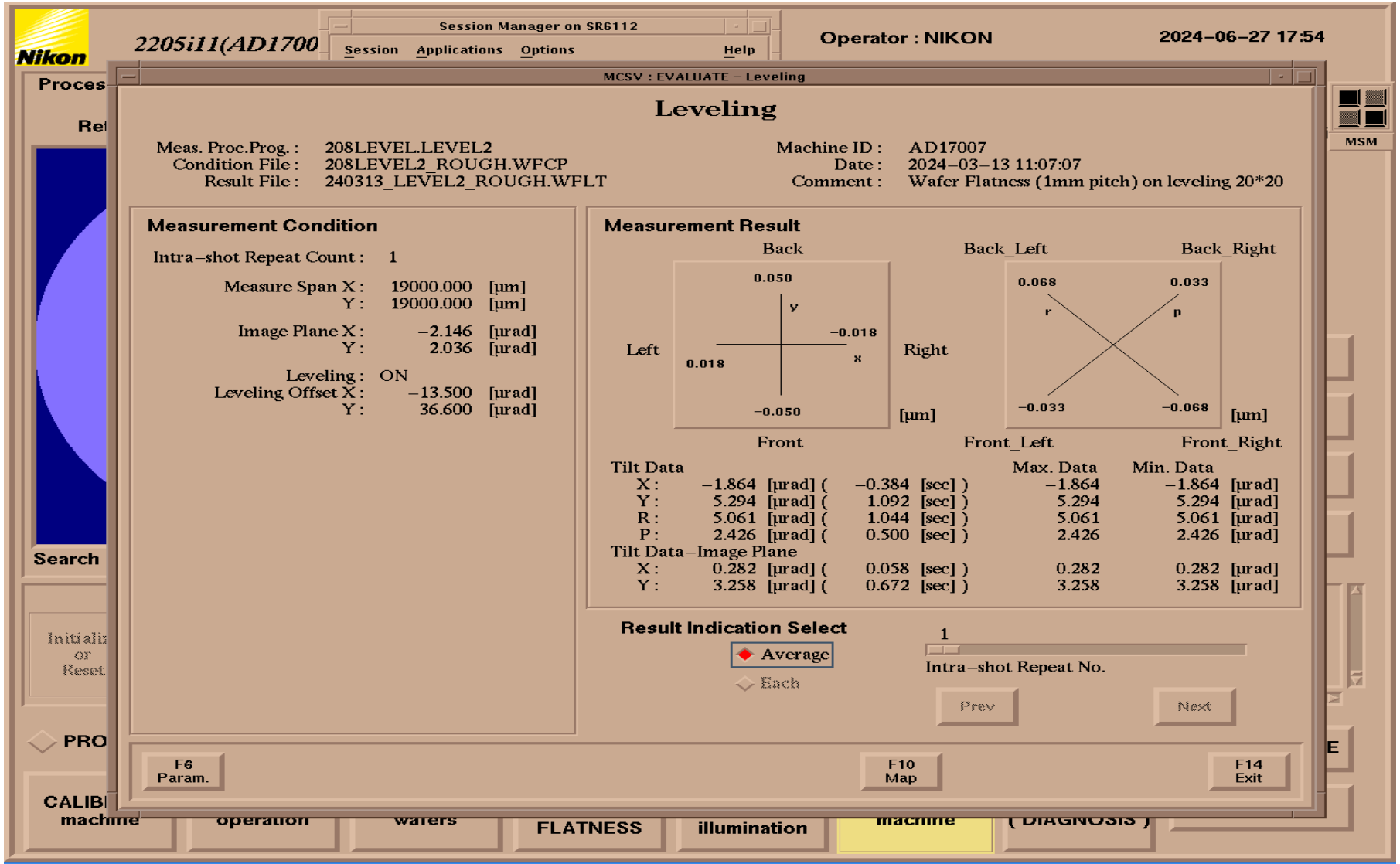
OEM Spec
Dose Accuracy < 1.5 %

Wafer Flatness



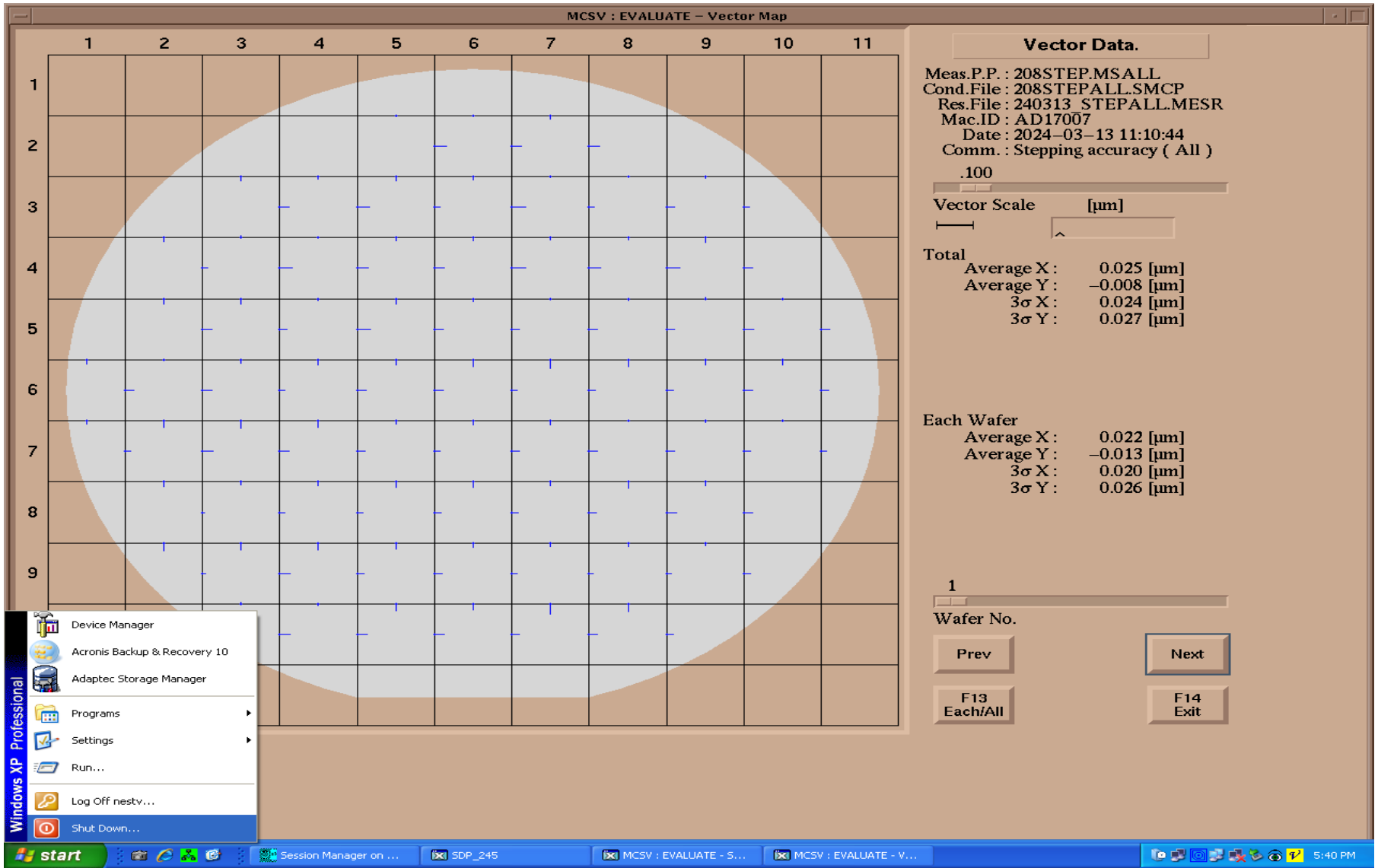
OEM Spec
WF < 2.5 um
LF < 0.8 um

Levelling



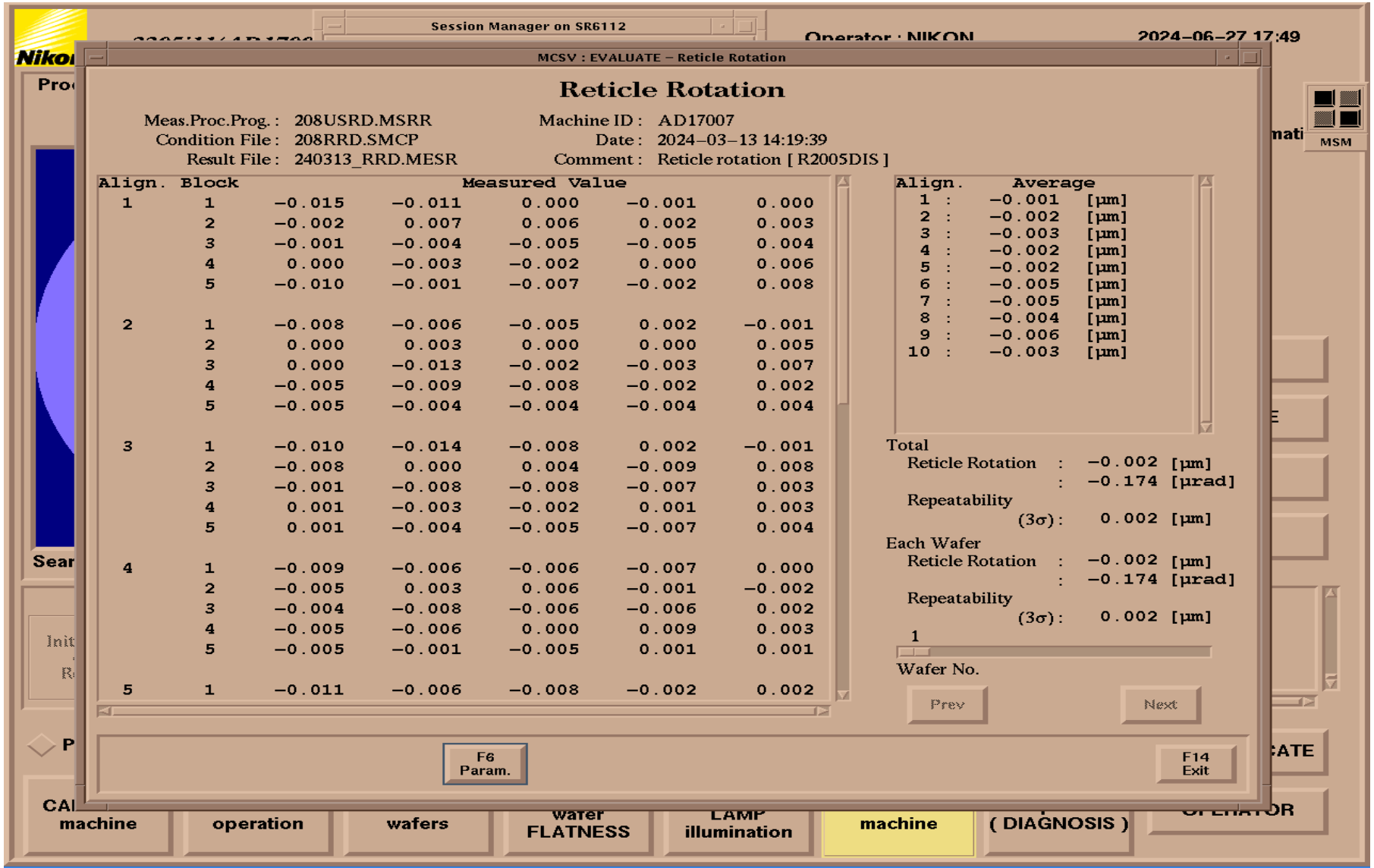
OEM Spec
X/Y < 7.2 urad

Stepping



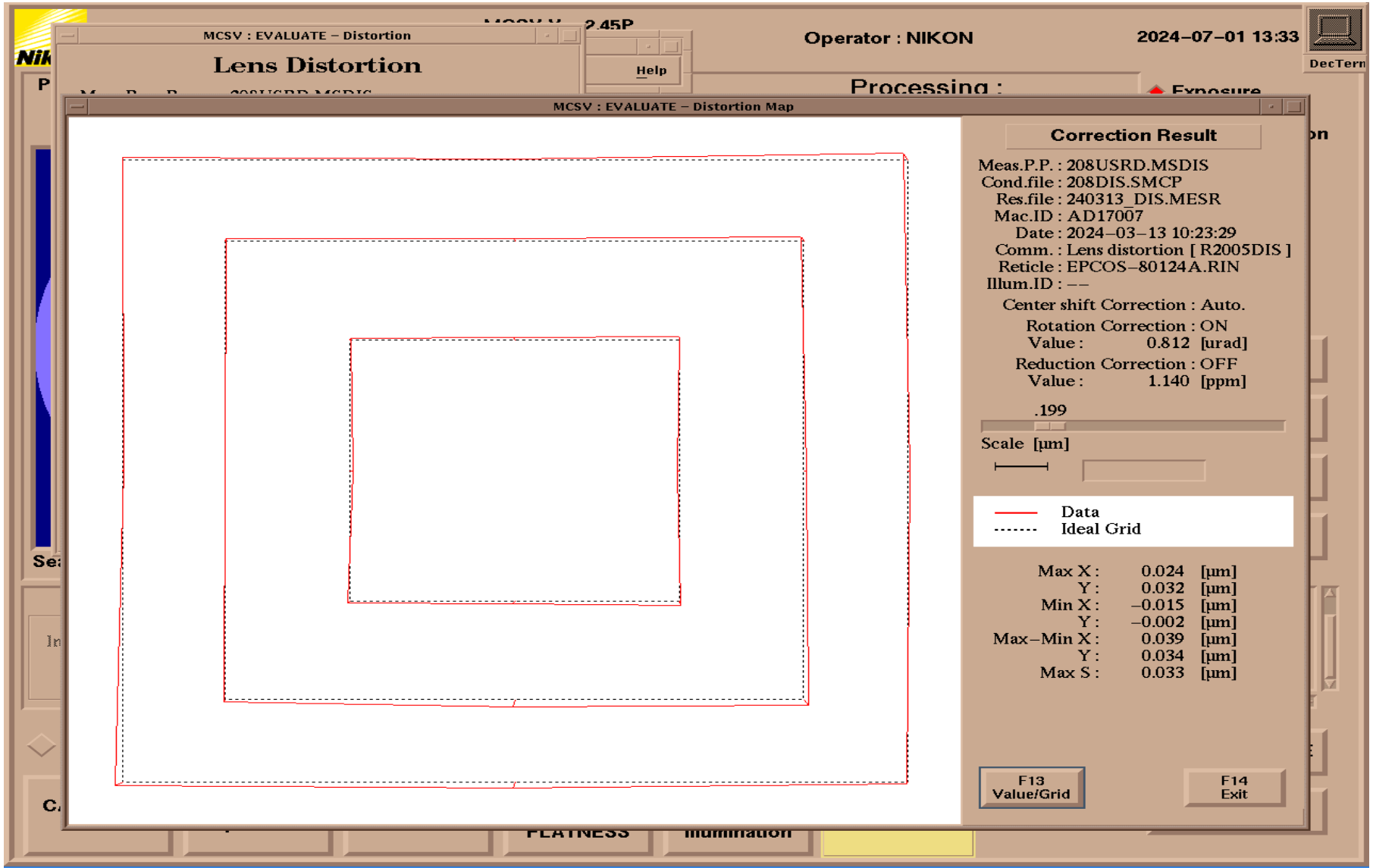
OEM Spec
X/Y 3 Sigma < 0.040 um

Reticle Rotation



OEM Spec
3 sigma + Mean < 15 um

LENS DISTORTION



OEM Spec < 0.040 um

Lens Inclination

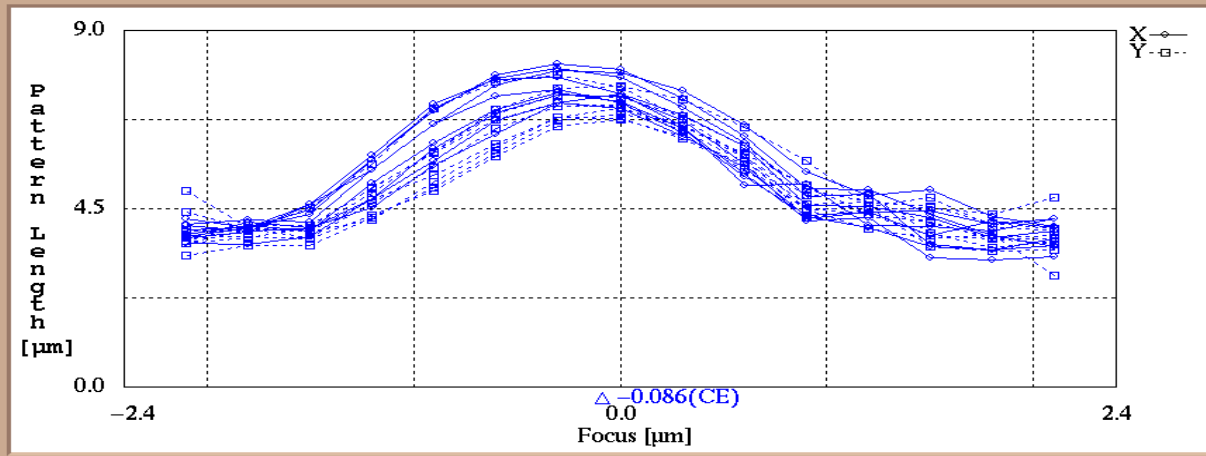
MCSV : EVALUATE – Field Inclination

Field Inclination

No.	Locate [µm] X	Locate [µm] Y	Best Focus [µm] V	Best Focus [µm] H	Best Focus [µm] V,H Ave.	Best Focus [µm] V–H	Max Length [µm] X	Max Length [µm] Y	Inc. [µm]
1	−9701.00	−9701.00	−0.044	−0.073	−0.059	0.029	7.162	6.812	0.001
2	−9700.00	0.00	−0.167	−0.207	−0.187	0.040	8.064	7.023	0.021
3	−9701.00	9701.00	0.009Mx	−0.173	−0.082	0.182	7.300	6.748	0.041
4	0.00	−9700.00	−0.265	−0.331Mn	−0.298	0.066	7.709	7.755	−0.020
5	0.00	0.00	−0.041	−0.130	−0.086	0.089	7.965	7.583	0.000
6	0.00	9700.00	−0.123	−0.312	−0.218	0.189	7.353	7.282	0.020
7	9701.00	−9701.00	−0.122	−0.226	−0.174	0.104	7.218	6.645	−0.041
8	9700.00	0.00	−0.094	−0.238	−0.166	0.144	7.947	7.037	−0.021
9	9701.00	9701.00	−0.050	−0.175	−0.113	0.125	7.021	6.552	−0.001

Meas.Proc.Prog. : 20MF09.MSINC09
Condition File : 20INCB09H.SMCP
Result File : 240313_INC09H.MESR
Machine ID : AD17007
Date : 2024–03–13 10:09:17
Comment : INC9 (0.5mic HV)

Reject Limit (Upper) :	12.000 [µm]
Reject Limit (Range) :	1.000 [µm]
Approximate Reject Limit :	1.000 [µm]
Focus Center on Exposure :	0.000 [µm]
Focus Step on Exposure :	0.300 [µm]
Focus Slice Level :	1.000 [µm]
Weight Dumping Rate :	1.000
Angle adjustment Value X :	------- [µrad]
Y :	------- [µrad]
Angle X :	−2.148 [µrad]
Angle Y :	2.036 [µrad]
Angle R :	2.958 [µrad]
Angle P :	−0.079 [µrad]
Max–Min :	0.340 [µm]
Curvature :	−0.021 [µm]
UR–LL :	−0.054 [µm]
UL–LR :	0.092 [µm]

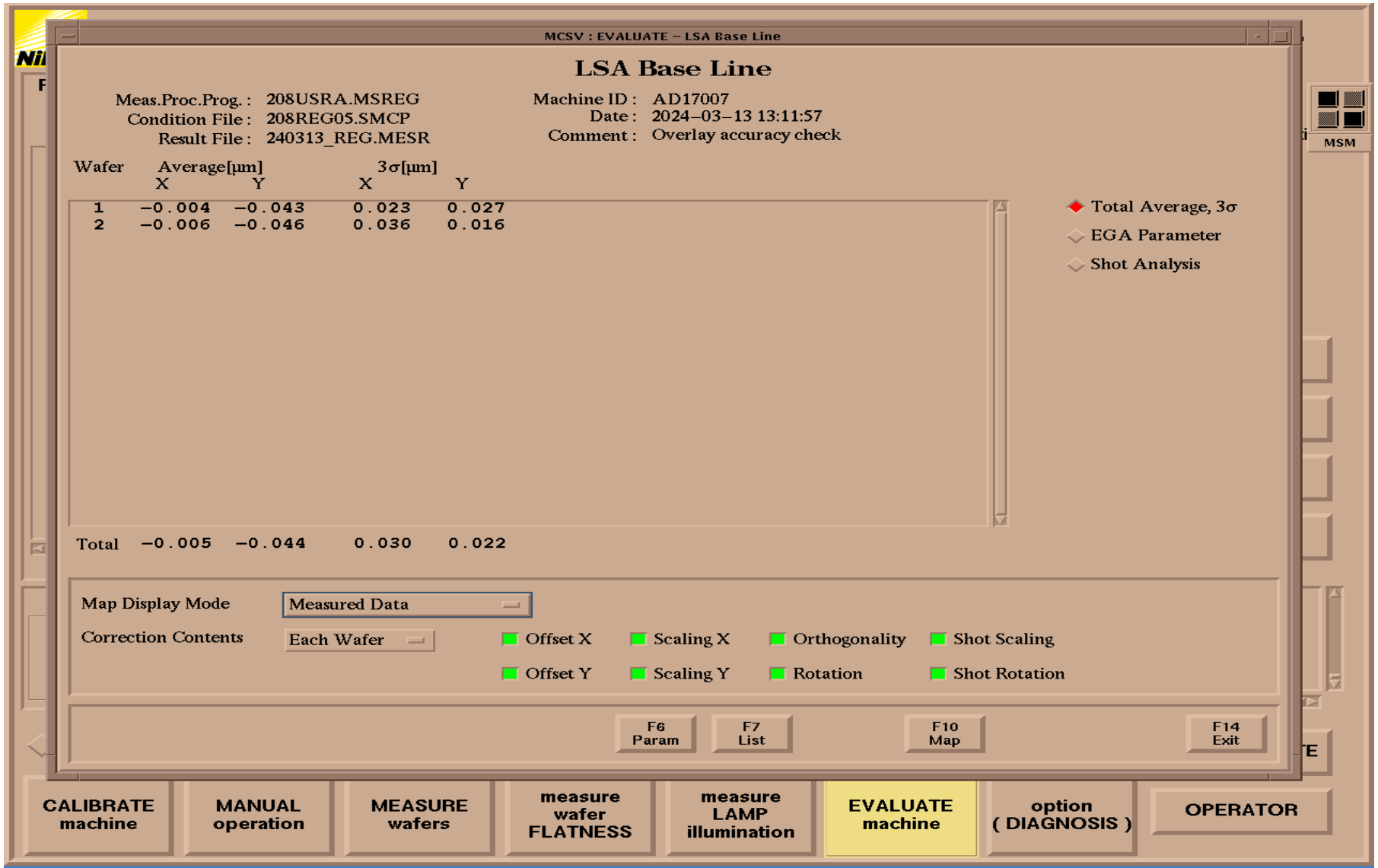


Object Wafer
Total
Each Wafer
1
Wafer No.
Prev
Next

F6 Param. | F7 List | F8 Summary | F9 Display | F10 Map | F14 Exit

OEM Spec
Max – Min < 0.4 um

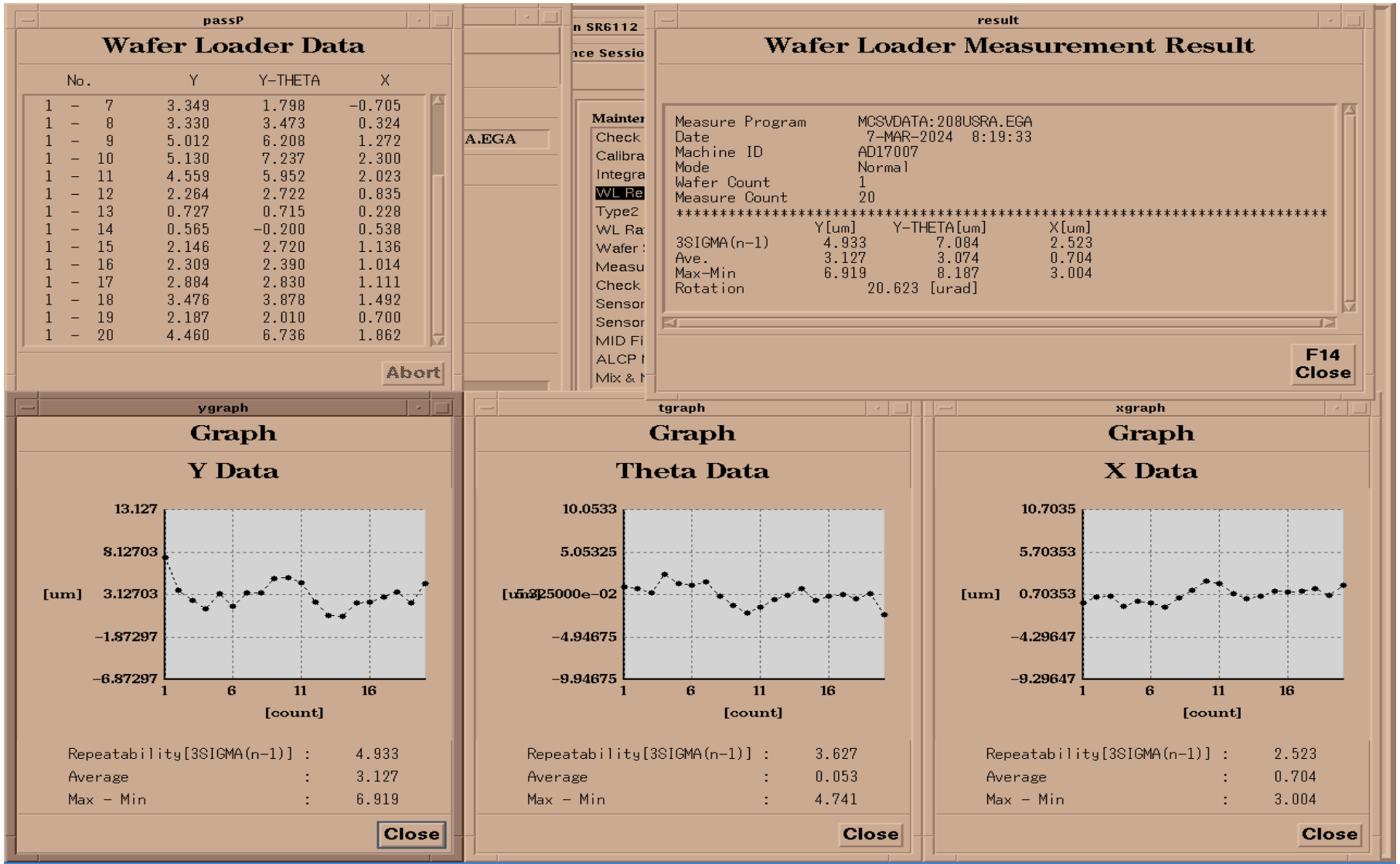
Overlay



OEM Spec
3 sig + Mean < 0.080 um

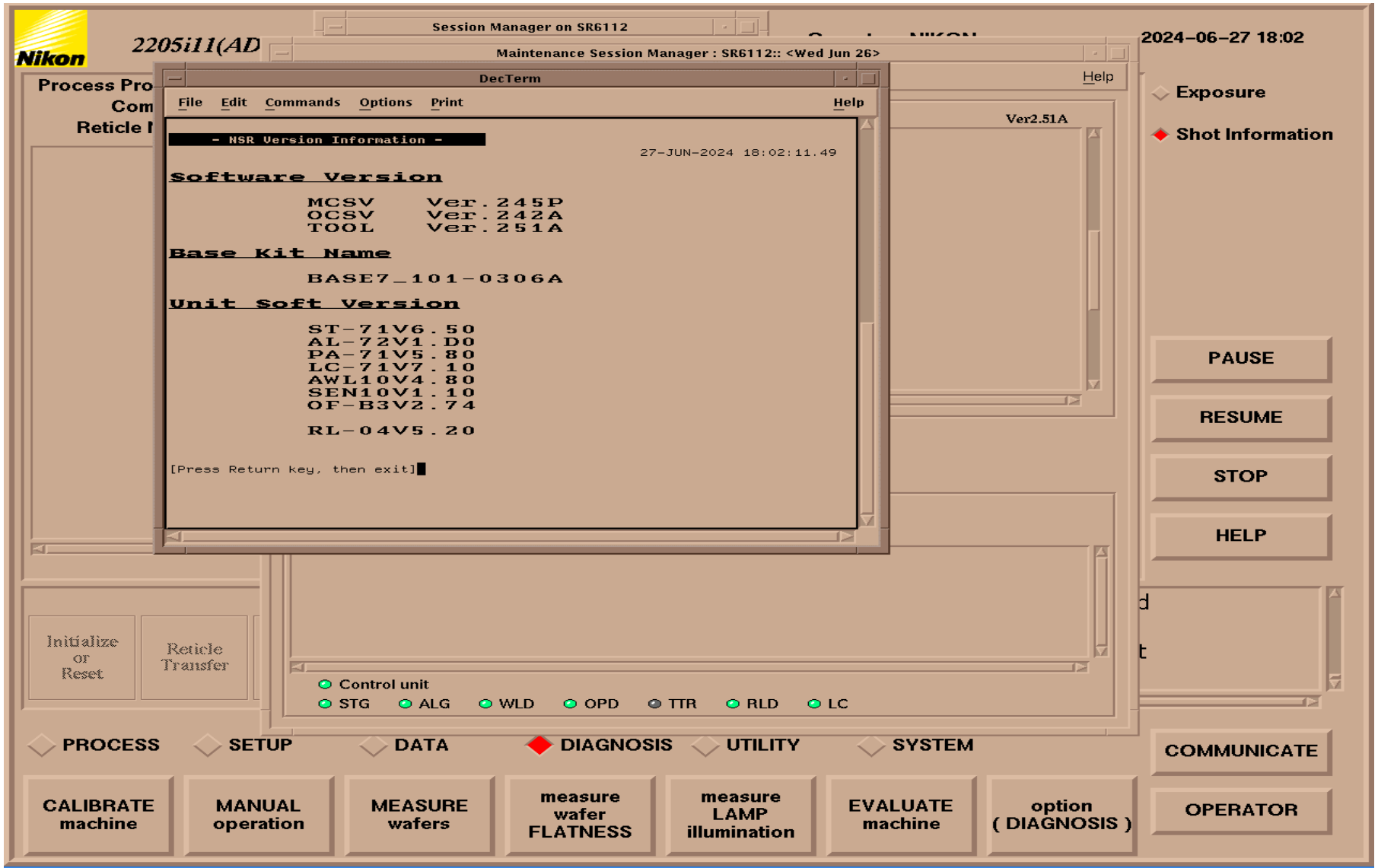
Means not dialled out here with software for Y.

Wafer Loader Repeatability



3 Sigma X/Y/T < 15um

Software


Session Manager on SR6112
Maintenance Session Manager : SR6112:: <Wed Jun 26>
2205i11(AD
2024-06-27 18:02
DecTerm
File Edit Commands Options Print Help
- NSR Version Information -
27-JUN-2024 18:02:11.49
Software Version
MCSV Ver.245P
OCSV Ver.242A
TOOL Ver.251A
Base Kit Name
BASE7_101-0306A
Unit Soft Version
ST-71V6.50
AL-72V1.D0
PA-71V5.80
LC-71V7.10
AWL10V4.80
SEN10V1.10
OF-B3V2.74
RL-04V5.20
[Press Return key, then exit]
Help
Ver2.51A
Exposure
Shot Information
PAUSE
RESUME
STOP
HELP
Initialize or Reset
Reticle Transfer
Control unit
STG ALG WLD OPD TTR RLD LC
PROCESS SETUP DATA DIAGNOSIS UTILITY SYSTEM
COMMUNICATE
OPERATOR
CALIBRATE machine
MANUAL operation
MEASURE wafers
measure wafer FLATNESS
measure LAMP illumination
EVALUATE machine
option (DIAGNOSIS)